P/N	SH	REV
610-90729-01	1	2.0

REVISIONS

ECO NO.	REV	DATE	DESCRIPTION	DRAWN	CHECKED	APPROVED
MILI61	1.0	02/26/19	INITIAL RELEASE	YJUN	MILI	MILI
MILI67	2.0	06/04/19	DESIGN UPDATE	YJUN	MILI	MILI
SUC-4	2.0	07/21/22	DESIGN UPDATE	ISJP	SUC	SUC

NOTES: UNLESS OTHERWISE SPECIFIED

1. SPECIFICATIONS/TOLERANCES:
   A. FABRICATE PER IPC-6012, CLASS 2, USING PROVIDED DATA FILES
   B. ALL SPECIFICATIONS USED SHALL BE PER THEIR LATEST REVISIONS.
   C. THE DIMENSIONS OF CIRCUIT FEATURES IN THE PROVIDED DATA MAY BE ADJUSTED ONLY TO COMPENSATE FOR PROCESS TOLERANCES; ADDING, REMOVING OR RELOCATING CIRCUIT FEATURES, INCLUDING NON-FUNCTIONAL PADS, IS NOT ALLOWED, AND THE DESIGN OF ALL PLANE STRUCTURES MUST BE MAINTAINED TO ENSURE PROPER ELECTRICAL PERFORMANCE.
   D. REMOVE ALL BURRS AND BREAK SHARP EDGES, .381 [.015] MAX RADIUS.
   E. PARENTHETICAL INFORMATION IS FOR REFERENCE ONLY.
   F. REPAIR OF PCB DEFECTS IS NOT PERMITTED.

2. DIELECTRIC MATERIAL:
   A. DIELECTRIC MATERIAL SHALL BE PER IPC-4101/99, /124, /126 OR /129 (RoHS COMPLIANT EPOXY-GLASS).
   B. MINIMUM DIELECTRIC THICKNESS SHALL BE .051 [.002] FOR REFERENCED STACK-UP DIMENSIONS OF.076 [.003] OR GREATER; IPC-6012 REQUIREMENTS SHALL OTHERWISE APPLY. SINGLE-PLY CONSTRUCTION IS ALLOWED.
   C. SEE LAYER STACK-UP FOR REQUIRED COPPER WEIGHTS AND THE FINISHED PCB THICKNESS. IF SPECIFIED, 1/3 OZ. STARTING FOIL MAY BE ACHIEVED BY 1/2 OZ. FOIL REDUCTION.
   D. FINISHED PCB THICKNESS SHALL BE MEASURED OVER LANDS AND/OR CONDUCTORS NOT COVERED BY SOLDER MASK.

3. DRILLING:
   A. VIA DIAMETERS (TOL. = +.051/- DRILL DIAMETER [+.0020/- DRILL DIAMETER]) SHALL BE VERIFIED BEFORE PLATING; ALL OTHER HOLE DIAMETERS SHALL BE VERIFIED AT FINAL INSPECTION.
   B. LAYER-TO-LAYER MISREGISTRATION SHALL BE .127 [.005] MAXIMUM.

4. SOLDER MASK:
   A. APPLY LPI SOLDER MASK USING PROVIDED DATA.
   B. SOLDER MASK SHALL BE PER IPC-SM-840, CLASS T, COLOR RED.
   C. THE DIMENSIONS OF SOLDER MASK-DEFINED PADS ON PLANES AND/OR WIDE CONDUCTORS SHALL NOT BE MODIFIED.

5. MARKING:
   A. MARK PCB PER PROVIDED DATA USING SILKSCREEN OR AUTOMATED INJET PROCESSING WITH PERMANENT, NON-CONDUCTIVE INK, COLOR WHITE.
   B. SUPPLIER ID AND TRACEABILITY INFORMATION SHALL BE APPLIED USING PERMANENT, NON-CONDUCTIVE INK, COLOR WHITE.
   C. INK SHALL NOT BE APPLIED TO ANY SOLDERABLE SURFACE.

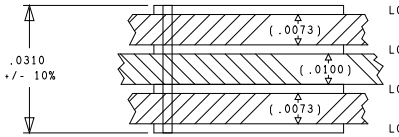
6. ELECTRICAL TEST:
   A. DESIGN VERIFICATION SHALL BE DONE PRIOR TO PCB FABRICATION USING SUPPLIED VALOR ODB++ DATABASE, OR GERBER DATA AND AN IPC-D-356 NETLIST.
   B. ALL PCBS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS AND SHORTS USING PROVIDED DATA.
   C. APPLY TEST STAMP IN NON-LEGEND AREA ON REAR SIDE OF PCB; OK TO APPLY TO PANEL RAILS IF SPACE DOES NOT PERMIT.

7. FINAL FINISH:
   A. FINAL FINISH ON ALL EXPOSED CONDUCTORS SHALL BE 2 MICROMETER GOLD IMMERSION.

   B. FINAL FINISH ON ALL THE GOLD FINGER BEVEL
      DEFAULT VALUE:20 DEGREES , DEPTH: 11.8MILS
      FINAL FINISH ON ALL EXPOSED GOLD FINGER SHALL BE 30 MICROMETER HARD GOLD PLATED.

8. IMPEDANCE:
   A. IMPEDANCE TOLERANCE SHALL BE +/- 10%.
   B. SEE LAYER STACK-UP FOR IMPEDANCE REQUIREMENTS.

9. IF PANELIZATION SPECIFICATIONS ARE PROVIDED, THE PCBS SHALL BE DELIVERED IN PANEL FORM. HOWEVER, THESE SPECIFICATIONS MAY BE CHANGED AS REQUIRED BY THE CONTRACT MANUFACTURER TO SUPPORT VOLUME ASSEMBLY REQUIREMENTS.



LAYER DESCRIPTION	START COPPER WT	SE IMP OHMS	SE TRACE WIDTH	REF LAYER	CPW SPACE	DIFF IMP OHMS	DIFF TRACE WIDTH/SPACE	REF LAYER	CPW SPACE
L01 - TOP	0.5 OZ	50	.0125	2	-----	---	.-----/.-----	---	-----
L02 - PLANE	0.5 OZ	--	-----	---	-----	---	----	---	-----
L03 - PLANE	0.5 OZ	--	-----	---	-----	---	----	---	-----
L04 - BOTTOM	0.5 OZ	--	.-----	---	-----	---	.-----/.-----	---	-----

STACK-UP (DIMENSIONS IN INCHES)

SEE BOM	SEE BOM
NEXT ASSY	USED ON
APPLICATION	

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UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN METRIC WITH INCHES IN BRACKETS
.XXX ±.064 [±.005] .XX ±.13 [±.01] ANGLES ±.5°

MATERIAL 2

FINISH 7

DO NOT SCALE DRAWING

APPROVALS	DATE
DRAWN ISJP	07/21/22
ENGINEER SUC	07/21/22
CHECKER SUC	07/21/22
QA -	-
PROJ. ENG. -	-

Infineon Technologies AG
IFAG MUC Am Campeon 1-15
85579 NEUBIBERG - GERMANY

TITLE
PCB FABRICATION,
CYW920819M2IPA1

SIZE	CAGE CODE	
D	-	610-90729-01

SCALE	SHEET	REV
1/1	1 OF 2	2.0

FAB NOTES REV 08/01/14

COMPUTER GENERATED DRAWING
DO NOT CHANGE MANUALLY

P/N	SH	REV
610-90729-01	2	2.0

REVISIONS

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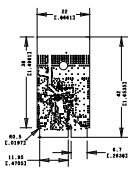

Dimensions are in mttric
with inches in brackets.

DRILL CHART: TOP to L02_GND
ALL UNITS ARE IN MILLIMETERS

FIGURE	FINISHED_SIZE	TOLERANCE_DRILL	PLATED	QTY
·	0.1	+0.05/-0.1	PLATED	251

DRILL CHART: L02_GND to L03_PWR-GND
ALL UNITS ARE IN MILLIMETERS

FIGURE	FINISHED_SIZE	TOLERANCE_DRILL	PLATED	QTY
·	0.15	+0.05/-0.05	PLATED	86

DRILL CHART: L03_PWR-GND to BOTTOM
ALL UNITS ARE IN MILLIMETERS

FIGURE	FINISHED_SIZE	TOLERANCE_DRILL	PLATED	QTY
·	0.1	+0.05/-0.1	PLATED	56

DRILL CHART: TOP to BOTTOM
ALL UNITS ARE IN MILLIMETERS

FIGURE	FINISHED_SIZE	TOLERANCE_DRILL	PLATED	QTY
·	0.15	+0.05/-0.05	PLATED	509
·	0.381	+0.05/-0.05	PLATED	1
	0.5	+0.05/-0.05	NON-PLATED	20
	3.5	+0.05/-0.05	NON-PLATED	1

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SIZE	CAGE CODE	610-90729-01
D	-	
SCALE 1/1	SHEET 2	REV 2.0

COMPUTER GENERATED DRAWING
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